

REMARKS

Claims 31 and 33-35 are pending.

In the Final Rejection dated August 19, 2003, the Examiner rejected claims 31-32 and 34-35 under 35 U.S.C. § 102(b) as being anticipated by Fjelstad U.S. Patent No. 5,989,939 (Fjelstad), and claim 33 under 35 U.S.C. § 103(a) as being unpatentable over Fjelstad in view of Bennett et al U.S. Patent No. 6,235,387 (Bennett). The Applicants traverse these rejections as follows.

Claim 31 has been amended to add subject matter previously present in claim 32. Now, claim 31 is directed to a method of manufacturing a semiconductor device, including steps of providing a film substrate; providing a plurality of semiconductor chips; arranging the semiconductor chips on device forming areas of the film substrate and electrically connecting the electrodes of the semiconductor chips with electrode members on the device forming areas; forming a resin encapsulator collectively sealing the device forming areas, electrode members, and semiconductor chips; and separating the resin encapsulator from the film substrate, thereby revealing the electrode members on one side of the resin encapsulator.

Turning to the Office Action, on page 2, item 2, the Examiner finds that Fjelstad discloses the claimed film substrate at 1, the claimed semiconductor chips at 6, and the claimed electrodes formed on the main surface of the semiconductor chips at 8. Further, the Examiner finds the claimed step of forming a resin encapsulator to be shown in Figure 6. Figure 6 shows the formation of a compliant layer 10 on substrate 1.

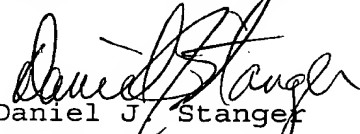
On page 3, item 3, the Examiner finds the claimed step of separating the resin encapsulator from the film substrate to be shown in Figure 11 of Fjelstad. Figure 11, however, shows the etching of a metallic layer 13 to remove it from the compliant layer 10 (corresponding to the claimed resin encapsulator, according to the rejection). As shown in Figure 11, the compliant layer 10 remains in complete contact with substrate 1. Therefore, the Applicants submit that Fjelstad does not disclose the claimed step of separating a resin encapsulator from a film substrate, thereby revealing electrode members on one side of the resin encapsulator.

The secondary reference to Bennett, applied in the obviousness rejection, does not show the claimed resin encapsulator and electrode members which are exposed by separating the resin encapsulator from the substrate. Thus,

the combination of Fjelstad also fails to teach the claimed invention.

In view of the foregoing amendments and remarks, the Applicants request reconsideration and reexamination of the rejection and allowance of the claims.

Respectfully submitted,


Daniel J. Stanger
Registration No. 32,846
Attorney for Applicant(s)

MATTINGLY, STANGER & MALUR, P.C.
1800 Diagonal Road, Suite 370
Alexandria, Virginia 22314
Telephone: (703) 684-1120
Facsimile: (703) 684-1157
Date: December 19, 2003